

Material Content Data Sheet

Umbrella Spec	IsoPACK™ 42		
Date	2012-03-19	**RoHS compliant**	Yes
Revision	3.0		

Construction element	*Material group*	*Materials*	*CAS-Nr. if applicable*	*Average mass [%]**	*Sum [%]*	*Traces*	*Comment*
chip	inorganic material	silicon	7440-21-3	0,30	0,30		
Base plate and substrate including metallisation	non noble metal	copper	7440-50-8	48,00	52,61		
	inorganic material	aluminium oxid	1344-28-1	1,60			
	non noble metal	tin	7440-31-5	2,76			
	noble metal	silver	7440-22-4	0,10			
	non noble metal	nickel	7440-02-0	0,15			
wire	non noble metal	aluminium	7429-90-5	0,30	0,30		
encapsulation	polymers	silicone gel		6,50	6,50		
housing	polymers	PBT		18,04	31,72		
	inorganic material	antimonytrioxide	1309-64-4	1,90			
	plastics	brominated resin		1,30			
	plastics	chlorinated resin		0,88			
	inorganic material	silicondioxide / glasfiber		9,60			
lead, finish and plating	non noble metal	copper	7440-50-8	4,50	8,60		
	ferrous metal	steel		3,40			
	non noble metal	zinc	7440-66-6	0,70			
	non noble metal	tin	7440-31-5			X	
	noble metal	silver	7440-22-4			X	
	non noble metal	nickel	7440-02-0			X	
deviation	<25%			Sum in total	100,0		

Weight range of product	**225**
Fluctuation margin	<25%

*) related to component weight
**) Weight of particular product, see technical product information

Important Remarks:

1) This document provides full declaration of all materials present in Infineon products above a threshold of 0,1 % b.w. (1000 ppm).
2) Trace concentrations (i.e. < 0,1 % b.w) present in products are marked with an "X" as far as they represent substances-of-concern.
A list of substances-of-concern can be found at http://www.infineon.com/soc.
3) All statements are based on our present knowledge and are subject to change at any time due to technical requirements and development.

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